

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Completes If Known

Application Number	09/687,263
Filing Date	October-12, 2000
First Named Inventor	Chok Chia
Group Art Unit	2827
Examiner Name	D. Graybill
Attorney Docket No.	68510 / 00-282

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U.S. PATENT DOCUMENTS

Examiner Initials	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number	Kind Code (if known)			
C		6,054,376		Balakrishnan	04-25-2000	
C		6,110,761		Ahmad	08-29-2000	
C		6,440,777		Cobbley et al.	08-27-2002	

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initials	Cite No.	Include name of author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where	T
C		"The Limits of Wirebond Technology: Is Flip-Chip Attach Now a Prerequisite for Advanced Packaging?", Kuzawinsky, Mark J., IBM MicroNews, 2000, Volume 6, No. 4, pages 1-9	
C		2002/0072150 - Author(s) - Cobbley	

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